

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

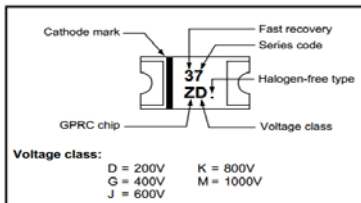
FEATURES

- Lead free product, compliance to RoHS
- GPRC (Glass passivated rectifier chip) inside
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0

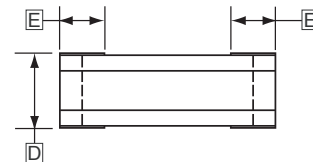
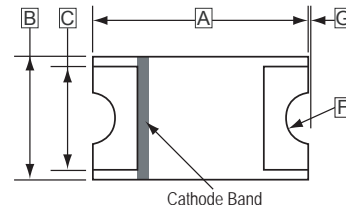
MECHANICAL DATA

- Case : Packed with FRP substrate and epoxy underfilled
- Terminals : Pure Tin plated (Lead-Free), solderable per MIL-STD-750, Method 2026.
- Weight : 0.012 gram

MARKING



1206



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	3.20	3.60	E	0.50	0.90
B	1.70	2.10	F	R 0.40	
C	1.60 TYP.		G	0.05 REF.	
D	0.86	1.16			

PACKAGE INFORMATION

Package	MPQ	Leader Size
1206	3K	13' inch

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load. For capacitive load, de-rate current by 20%.)

Parameter	Symbol	Part Number					Unit
		SCDF103	SCDF104	SCDF105	SCDF106	SCDF107	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	200	400	600	800	1000	V
Maximum DC Blocking Voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average Forward	$I_{F(AV)}$	1					A
Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30					A
Maximum Instantaneous Forward Voltage @ 1A	V_F	1.3					V
Maximum Repetitive peak reverse current	$T_A=25^\circ\text{C}$	1					μA
	$T_A=125^\circ\text{C}$	30					
Maximum Reverse Recovery Time ¹	T_{RR}	250		300			nS
Typical Thermal Resistance ³	$R_{\theta JC}$	40					$^\circ\text{C/W}$
Typical Thermal Resistance ³	$R_{\theta JA}$	130					$^\circ\text{C/W}$
Typical Thermal Resistance ^{3,4}	$R_{\theta JL}$	40					$^\circ\text{C/W}$
Typical Junction Capacitance ²	C_J	15					pF
Operating & Storage Temperature	T_J, T_{STG}	-50~125, -65~150					$^\circ\text{C}$

Notes:

1. Reverse Recovery Time test condition : $I_F=0.5\text{A}$, $I_R=1\text{A}$, $I_{RR}=0.25\text{A}$
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. Thermal resistance from junction to ambient and from junction to lead P.C.B. mounted on 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.
4. The thermal resistance in measured over the centered point of the copper pad.
5. Preliminary draft

RATINGS AND CHARACTERISTIC CURVES

FIG.1 - FORWARD CURRENT DERATING CURVE

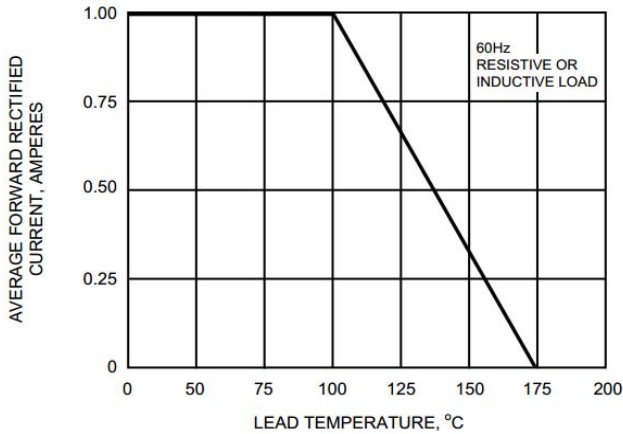


FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

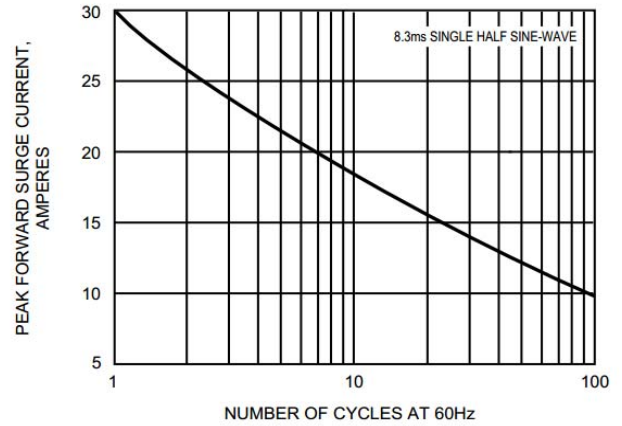


FIG.3 - TYPICAL JUNCTION CAPACITANCE

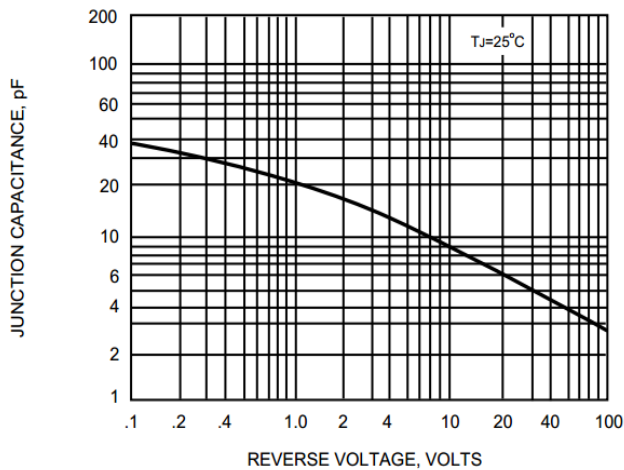


FIG.4 - NON-REPETITIVE PEAK FORWARD SURGE CURRENT SINE WAVEFORM

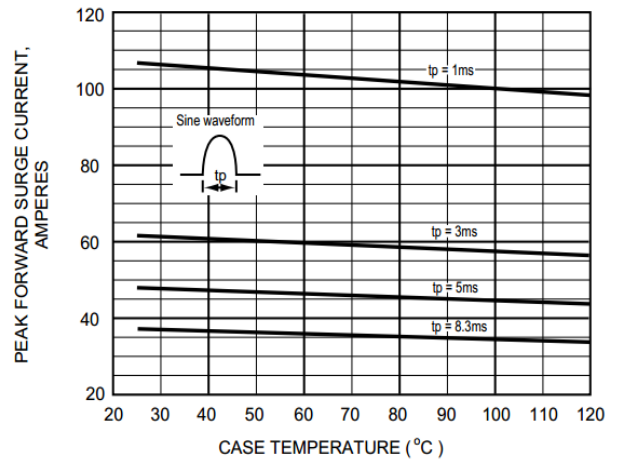


FIG.5 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

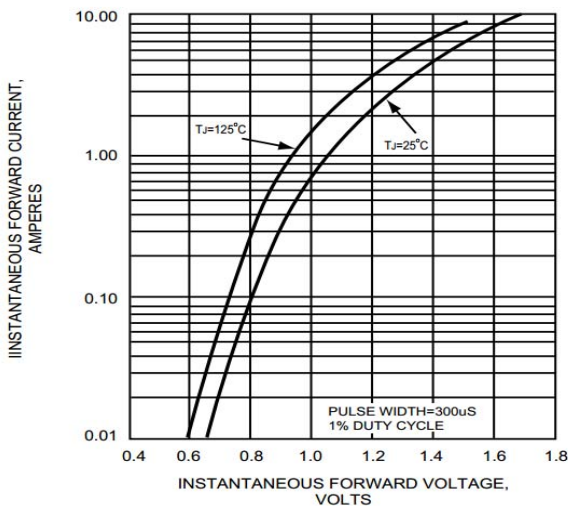


FIG.6 - TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT

